

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3160396

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the SECOND INVENTORS NAME previously recorded on Reel 032130 Frame 0493. Assignor(s) hereby confirms the SECOND INVENTORS NAME SHOULD BE UNNIKRISHNAN VADAKKANMARUVEEDU.
CONVEYING PARTY DATA	
Name	Execution Date
ANKUR JAIN	09/22/2014
UNNIKRISHNAN VADAKKANMARUVEEDU	12/15/2014
VINAY MITTER	10/20/2014
RECEIVING PARTY DATA	
Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13963248
CORRESPONDENCE DATA	
Fax Number:	(703)391-2901
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	7033912900
Email:	ptonoticesqc@marburylaw.com
Correspondent Name:	THE MARBURY LAW GROUP, PLLC
Address Line 1:	11800 SUNRISE VALLEY DRIVE
Address Line 2:	15TH FLOOR
Address Line 4:	RESTON, VIRGINIA 20191
ATTORNEY DOCKET NUMBER:	130990 / 1376-1243
NAME OF SUBMITTER:	ROBERT M. HANSEN
SIGNATURE:	/Robert M. Hansen/
DATE SIGNED:	12/23/2014
Total Attachments: 12	
source=130990_CorrectedAssignment_FILED#page1.tif	

source=130990_CorrectedAssignment_FILED#page2.tif
source=130990_CorrectedAssignment_FILED#page3.tif
source=130990_CorrectedAssignment_FILED#page4.tif
source=130990_CorrectedAssignment_FILED#page5.tif
source=130990_CorrectedAssignment_FILED#page6.tif
source=130990_CorrectedAssignment_FILED#page7.tif
source=130990_CorrectedAssignment_FILED#page8.tif
source=130990_CorrectedAssignment_FILED#page9.tif
source=130990_CorrectedAssignment_FILED#page10.tif
source=130990_CorrectedAssignment_FILED#page11.tif
source=130990_CorrectedAssignment_FILED#page12.tif



UNITED STATES PATENT AND TRADEMARK OFFICE

UNDER SECRETARY OF COMMERCE FOR INTELLECTUAL PROPERTY AND
DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE

FEBRUARY 5, 2014

PTAS

THE MARBURY LAW GROUP, PLLC
11800 SUNRISE VALLEY DRIVE
15TH FLOOR
RESTON, VA 20191

502665188

UNITED STATES PATENT AND TRADEMARK OFFICE
NOTICE OF RECORDATION OF ASSIGNMENT DOCUMENT

THE ENCLOSED DOCUMENT HAS BEEN RECORDED BY THE ASSIGNMENT RECORDATION BRANCH OF THE U.S. PATENT AND TRADEMARK OFFICE. A COMPLETE COPY IS AVAILABLE AT THE ASSIGNMENT SEARCH ROOM ON THE REEL AND FRAME NUMBER REFERENCED BELOW.

PLEASE REVIEW ALL INFORMATION CONTAINED ON THIS NOTICE. THE INFORMATION CONTAINED ON THIS RECORDATION NOTICE REFLECTS THE DATA PRESENT IN THE PATENT AND TRADEMARK ASSIGNMENT SYSTEM. IF YOU SHOULD FIND ANY ERRORS OR HAVE QUESTIONS CONCERNING THIS NOTICE, YOU MAY CONTACT THE ASSIGNMENT RECORDATION BRANCH AT 571-272-3350. PLEASE SEND REQUEST FOR CORRECTION TO: U.S. PATENT AND TRADEMARK OFFICE, MAIL STOP: ASSIGNMENT RECORDATION BRANCH, P.O. BOX 1450, ALEXANDRIA, VA 22313.

RECORDATION DATE: 02/04/2014

REEL/FRAME: 032130/0493
NUMBER OF PAGES: 5

BRIEF: ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS).

DOCKET NUMBER: 130990 / 1376-1243

ASSIGNOR:

JAIN, ANKUR

DOC DATE: 01/31/2014

ASSIGNOR:

VADAKKANMARUVEEDU, ~~JMM~~

DOC DATE: 01/31/2014

ASSIGNOR:

MITTER, VINAY

DOC DATE: 01/31/2014

ASSIGNEE:

QUALCOMM INCORPORATED
5775 MOREHOUSE DRIVE
SAN DIEGO, CALIFORNIA 92121-1714

APPLICATION NUMBER: 13963248

FILING DATE: 08/09/2013

PATENT NUMBER:

ISSUE DATE:

TITLE: THERMAL MITIGATION ADAPTATION FOR A MOBILE ELECTRONIC DEVICE

ASSIGNMENT RECORDATION BRANCH
PUBLIC RECORDS DIVISION

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2711796

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>ANKUR JAIN</td> <td>01/31/2014</td> </tr> <tr> <td>UNNI VADAKKANMARUVEEDU - UNNI KRISHNAN NADAKKORMANUVEEDU</td> <td>01/31/2014</td> </tr> <tr> <td>VINAY MITTER</td> <td>01/31/2014</td> </tr> </tbody> </table>		Name	Execution Date	ANKUR JAIN	01/31/2014	UNNI VADAKKANMARUVEEDU - UNNI KRISHNAN NADAKKORMANUVEEDU	01/31/2014	VINAY MITTER	01/31/2014		
Name	Execution Date										
ANKUR JAIN	01/31/2014										
UNNI VADAKKANMARUVEEDU - UNNI KRISHNAN NADAKKORMANUVEEDU	01/31/2014										
VINAY MITTER	01/31/2014										
RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>QUALCOMM INCORPORATED</td> </tr> <tr> <td>Street Address:</td> <td>5775 MOREHOUSE DRIVE</td> </tr> <tr> <td>City:</td> <td>SAN DIEGO</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>92121-1714</td> </tr> </table>		Name:	QUALCOMM INCORPORATED	Street Address:	5775 MOREHOUSE DRIVE	City:	SAN DIEGO	State/Country:	CALIFORNIA	Postal Code:	92121-1714
Name:	QUALCOMM INCORPORATED										
Street Address:	5775 MOREHOUSE DRIVE										
City:	SAN DIEGO										
State/Country:	CALIFORNIA										
Postal Code:	92121-1714										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13963248</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13963248						
Property Type	Number										
Application Number:	13963248										
CORRESPONDENCE DATA											
Fax Number:	(703)391-2901										
Phone:	7033912900										
Email:	ptonoticesqc@marburylaw.com										
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>											
Correspondent Name:	THE MARBURY LAW GROUP, PLLC										
Address Line 1:	11800 SUNRISE VALLEY DRIVE										
Address Line 2:	15TH FLOOR										
Address Line 4:	RESTON, VIRGINIA 20191										
ATTORNEY DOCKET NUMBER:	130990 / 1376-1243										
NAME OF SUBMITTER:	ROBERT M. HANSEN										
Signature:	/Robert M. Hansen/										

ASSIGNMENT

WHEREAS, WE,

1. **Ankur Jain**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;
2. **Unnikrishnan VADAKKANMARUVEEDU**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego; and
3. **Vinay Mitter**, a citizen of the United States, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to THERMAL MITIGATION ADAPTATION FOR A MOBILE ELECTRONIC DEVICE (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS under the Patent Cooperation Treaty (PCT) or in the United States, including but not limited to International Patent Application No(s). 13/963,248, filed August 9, 2013, Qualcomm Reference No. 130990, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all nonprovisional applications, national phase applications, divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

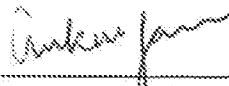
AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at SAN DIEGO, on 9/22/2014
LOCATION DATE


Ankur Jain

Done at _____, on _____
LOCATION DATE

Unnikrishnan VADAKKANMARUVEEDU

Done at _____, on _____
LOCATION DATE

Vinay Mitter

ASSIGNMENT

WHEREAS, WE,

1. **Ankur Jain**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;
2. **Unnikrishnan VADAKKANMARUVEEDU**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego; and
3. **Vinay Mitter**, a citizen of the United States, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to THERMAL MITIGATION ADAPTATION FOR A MOBILE ELECTRONIC DEVICE (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS under the Patent Cooperation Treaty (PCT) or in the United States, including but not limited to International Patent Application No(s). 13/963,248, filed August 9, 2013, Qualcomm Reference No. 130990, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all nonprovisional applications, national phase applications, divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

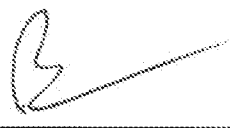
AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE **Ankur Jain**

Done at San Diego, on 12/15/14
LOCATION DATE 
Unnikrishnan VADAKKANMARUVEEDU

Done at _____, on _____
LOCATION DATE **Vinay Mitter**

ASSIGNMENT

WHEREAS, WE,

1. **Ankur Jain**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;
2. **Unnikrishnan VADAKKANMARUVEEDU**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego; and
3. **Vinay Mitter**, a citizen of the United States, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to THERMAL MITIGATION ADAPTATION FOR A MOBILE ELECTRONIC DEVICE (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS under the Patent Cooperation Treaty (PCT) or in the United States, including but not limited to International Patent Application No(s). 13/963,248, filed August 9, 2013, Qualcomm Reference No. 130990, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all nonprovisional applications, national phase applications, divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE **Ankur Jain**

Done at _____, on _____
LOCATION DATE **Unnikrishnan VADAKKANMARUVEEDU**

Done at San Diego, on 10/28/14
LOCATION DATE **Vinay Mitter**